

3EC-M3S-HTE

- 於回火後之高伸率及高耐曲折特性, 等同於壓延銅箔(RA)。
High Elongation and flexibility after annealing, equally with RA copper foil.
- 於S面進行表面處理, 具較3EC-HTE更低的粗糙度。
Lower profile compare with 3EC-HTE because of S-side surface treatment.
- 自2011年起日本、台灣和馬來西亞等3地均已量產, 提供穩定的銅箔供貨。
Stable supply is available because of 3-factory-production.

用途/Application

- 軟性電路板
/Flexible Print Board

構成/Composition



生產地點/Production Site

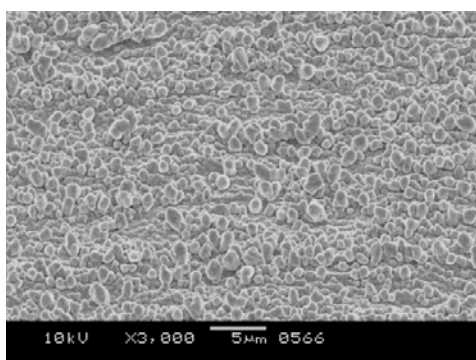
- 日本/Japan
- 馬來西亞/Malaysia

代表性特性數據/Representative

	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
3EC-M3S-HTE	12	107	2.5	390	6	0.8
	18	153	2.5	390	10	0.9

※上述表列為代表性數據非保證值
This is representative data, not guaranteed.

處理面/Laminate side



阻劑面/ resist side

